

ABSTRACT

A pressure sensitive adhesive film (50) of the present invention is a pressure sensitive adhesive film used to temporarily fix
5 electronic components when sealing the electronic components with a sealing material in an electronic device manufacturing step, the film including a pressure sensitive adhesive resin layer (A) for temporarily fixing the electronic components, a pressure sensitive adhesive resin layer (B) used for attaching to a support substrate
10 and of which an adhesive force is decreased by an external stimulus, and an intermediate layer (C) provided between the pressure sensitive adhesive resin layer (A) and the pressure sensitive adhesive resin layer (B). A storage elastic modulus E' at 120°C of the intermediate layer (C) is 1.0×10^5 Pa or more and 8.0×10^6 Pa or less, and a loss
15 tangent ($\tan \delta$) at 120°C of the intermediate layer (C) is 0.1 or less.